

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10755042
<b>Filing Date:</b>	09-Jan-2004
<b>Title of Invention:</b>	Integrated chip package structure using silicon substrate and method of manufacturing the same
<b>First Named Inventor/Applicant Name:</b>	Mou-Shiung Lin
<b>Filer:</b>	Dennis Alan Duchene/NICOLE SAN NICOLAS
<b>Attorney Docket Number:</b>	085027-0104

Filed as Large Entity

### Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>130</b>